BAS21HT1

Preferred Device

High Voltage Switching Diode

Features

• Pb–Free Packages are Available

MAXIMUM RATINGS

Symbol	Rating	Value	Unit
V _R	Continuous Reverse Voltage	250	Vdc
V _{RRM}	Repetitive Peak Reverse Voltage	250	Vdc
١ _F	I _F Peak Forward Current		mAdc
I _{FM(surge)}	I _{FM(surge)} Peak Forward Surge Current		mAdc

THERMAL CHARACTERISTICS

Symbol	Characteristic	Max	Unit
PD	Total Device Dissipation FR–5 Board, (Note 1) $T_A = 25^{\circ}C$	200	mW
	Derate above 25°C	1.57	mW/°C
$R_{ heta JA}$	Thermal Resistance, Junction-to-Ambient	635	°C/W
T _J , T _{stg}	Junction and Storage Temperature Range	–55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 Minimum Pad

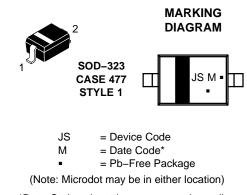


ON Semiconductor®

http://onsemi.com

HIGH VOLTAGE SWITCHING DIODE

1 0 2 CATHODE ANODE



*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
BAS21HT1	SOD-323	3000/Tape & Reel
BAS21HT1G	SOD-323 (Pb-Free)	3000/Tape & Reel

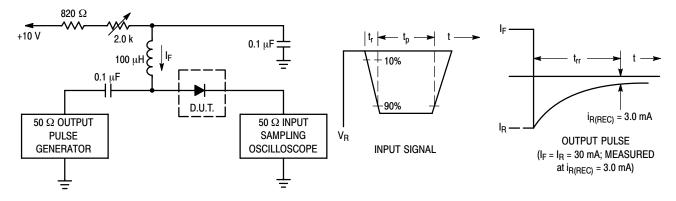
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

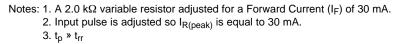
Preferred devices are recommended choices for future use and best overall value.

BAS21HT1

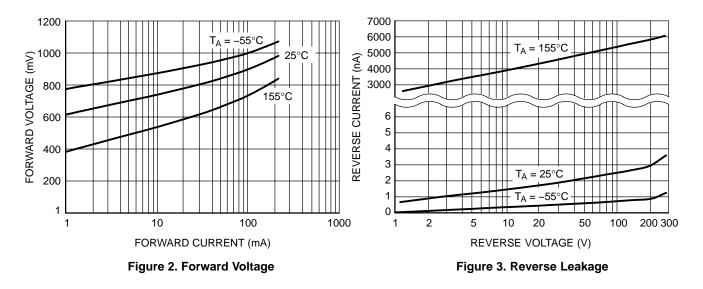
ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Reverse Voltage Leakage Current ($V_R = 200 \text{ Vdc}$) ($V_R = 200 \text{ Vdc}$, $T_J = 150^{\circ}\text{C}$)	Ι _R		0.1 100	μAdc
Reverse Breakdown Voltage (I _{BR} = 100 μAdc)	V _(BR)	250	-	Vdc
Forward Voltage (I _F = 100 mAdc) (I _F = 200 mAdc)	VF		1000 1250	mV
Diode Capacitance ($V_R = 0, f = 1.0 \text{ MHz}$)	CD	-	5.0	pF
Reverse Recovery Time ($I_F = I_R = 30 \text{ mAdc}, R_L = 100 \Omega$)	t _{rr}	-	50	ns





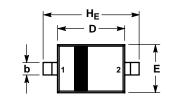


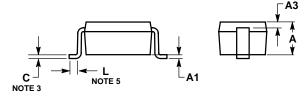


BAS21HT1

PACKAGE DIMENSIONS

SOD-323 PLASTIC PACKAGE CASE 477-02 ISSUE G





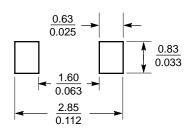
NOTES

- DIMENSIONING AND TOLERANCING PER ANSI 1. Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS.
- LEAD THICKNESS SPECIFIED PER LF DRAWING WITH SOLDER PLATING.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- 5. DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF		0.006 REF			
b	0.25	0.32	0.4	0.010	0.012	0.016
С	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
Е	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105

STYLE 1: PIN 1. CATHODE 2. ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D

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